

Electrolube® LGF200

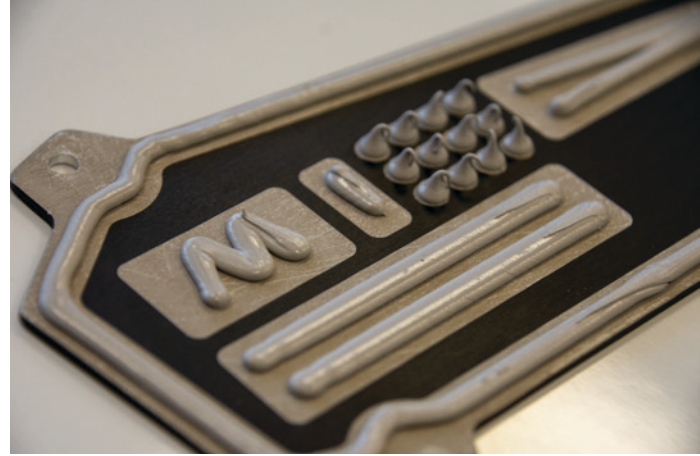
Thermal Interface Materials

Electrolube® LGF200 is a thermal interface material designed for easy processing. This thermally conductive liquid gap filler features a two-component, cure-in-place formulation and is silicone-based. With a high thermal conductivity of 2W/m-K, LGF200 provides excellent heat transfer between mating surfaces and significantly helps prevent device overheating.

Thanks to its shear-thinning behavior, LGF200 dispenses with ease and precision, holding its form without slumping. The material offers excellent adhesion to surfaces, simplifying the application process. Once dispensed, LGF200 conforms to mating surfaces, effectively filling air gaps and ensuring superior wet-out. Curing can be completed at room temperature or accelerated with heat, resulting in a soft, fully cured elastomer. This elastomer stays securely in place, preventing pump-out and providing long-term reliability for critical applications.

KEY FEATURES

- **Thermal conductivity:** 2 W/m-K for optimal heat transfer
- **Two-part formulation** with a 1:1 mix ratio
- **Room temperature cure**, with the option for accelerated curing using heat
- **Wide operating temperature range:** -50 to +200°C
- Cures to a **low hardness**, flexible polymer, minimizing stress on PCBs, components and solder joints
- **Low thermal impedance** due to excellent wet-out
- **No pump-out** or dry-out, maintaining stable interface integrity
- Available in **various pack-sizes**
- Dual cartridges sets are **made with recycled plastics**, reducing CO2 footprint



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